Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

- 1. (Currently Amended) A superconducting wire comprising a metal substrate and an overlying superconducting layer [[(3)]], wherein said metal substrate is a textured metal substrate [[(1)]] planarized to have a surface layer extending from a surface thereof to a depth of 300 nm with a crystal axis offset relative to an orientation axis by at most 25°, and a surface roughness R_{P-V} of at most 150 nm.
- 2. (Currently Amended) The superconducting wire according to claim 1, wherein said textured metal substrate [[(1)]] underlies an intermediate layer [[(2)]] and said intermediate layer [[(2)]] underlies said superconducting layer [[(3)]].
- 3. (Currently Amended) A method of producing a superconducting wire, comprising the steps of:

planarizing a textured metal substrate [[(1)]] to have a surface layer extending from a surface thereof to a depth of 300 nm with a crystal axis offset relative to an orientation axis by at most 25°, and a surface roughness R_{P-V} of at most 150 nm; and

depositing a superconducting layer (3) on said textured metal substrate planarized.

- 4. (Currently Amended) The method according to claim 3, further comprising the step of thermally treating said textured metal substrate [[(1)]] in a reducing atmosphere at least once after the step of planarizing said textured metal substrate [[(1)]] and before the step of depositing said superconducting layer [[(3)]] on said textured metal substrate [[(1)]] planarized.
- 5. (Currently Amended) The method according to claim 3, further comprising the step of thermally treating said textured metal substrate [[(1)]] in a vacuumed atmosphere at least once after the step of planarizing said textured metal substrate [[(1)]] and before the

step of depositing said superconducting layer [[(3)]] on said textured metal substrate [[(1)]] planarized.

- 6. (Currently Amended) The method according to claim 3, wherein the step of planarizing said textured metal substrate [[(1)]] is performed by at least one of: mirror finished rolling; mechanochemistry; electrolytic polishing; and chemical polishing.
- 7. (Currently Amended) The method according to claim 6, further comprising the step of thermally treating said textured metal substrate [[(1)]] in a reducing atmosphere at least once after the step of planarizing said textured metal substrate [[(1)]] and before the step of depositing said superconducting layer [[(3)]] on said textured metal substrate [[(1)]] planarized.
- 8. (Currently Amended) The method according to claim 6, further comprising the step of thermally treating said textured metal substrate [[(1)]] in a vacuumed atmosphere at least once after the step of planarizing said textured metal substrate [[(1)]] and before the step of depositing said superconducting layer [[(3)]] on said textured metal substrate [[(1)]] planarized.
- 9. (Currently Amended) The method according to claim 3, further comprising the steps of:

depositing an intermediate layer [[(2)]] on said textured metal substrate [[(1)]]; and depositing said superconducting layer [[(3)]] on said intermediate layer [[(2)]].

- 10. (Currently Amended) The method according to claim 9, further comprising the step of thermally treating said textured metal substrate [[(1)]] in a reducing atmosphere at least once after the step of planarizing said textured metal substrate [[(1)]] and before the step of depositing said intermediate layer [[(2)]] on said textured metal substrate [[(1)]] planarized.
- 11. (Currently Amended) The method according to claim 9, further comprising the step of thermally treating said textured metal substrate [[(1)]] in a vacuumed atmosphere at least once after the step of planarizing said textured metal substrate [[(1)]] and before the

step of depositing said intermediate layer [[(2)]] on said textured metal substrate [[(1)]] planarized.

- 12. (Currently Amended) The method according to claim 9, wherein the step of planarizing said textured metal substrate [[(1)]] is performed by at least one of: mirror finished rolling; mechanochemistry; electrolytic polishing; and chemical polishing.
- 13. (Currently Amended) The method according to claim 12, further comprising the step of thermally treating said textured metal substrate [[(1)]] in a reducing atmosphere at least once after the step of planarizing said textured metal substrate [[(1)]] and before the step of depositing said intermediate layer [[(2)]] on said textured metal substrate [[(1)]] planarized.
- 14. (Currently Amended) The method according to claim 12, further comprising the step of thermally treating said textured metal substrate [[(1)]] in a vacuumed atmosphere at least once after the step of planarizing said textured metal substrate [[(1)]] and before the step of depositing said intermediate layer [[(2)]] on said textured metal substrate [[(1)]] planarized.